

Specification GB200 Cold Plate

P/N	GB200 Cold Plate
Platform	GB200
Type	Grace Blackwell Superchip
Architecture	2x Blackwell GPU + Grace CPU
TDP(W)	2x1200W GPU +300W CPU
Total TDP(W)	2700W
Liquid Cooling module Size (WxDxH)	189.5 x 270.4 x 28.5 mm
Liquid Cooling module Weight(KG)	2.9 KG
Liquid coolant	PG25
Quick connector	CEJN UQD04
Liquid Tube Material	Stainless steel
Inlet Flow Temperature	40°C
Inlet Flow Rate of Liquid	1.8 LPM
Liquid pressure drop	<10 psi

Dimension Details



GB200 Cold Plate

Key Features

- Cooling capacity : 2700W
- Compatible with DI Water/PG25 coolant
- Suitable for GB200 Superchip server and 1U chassis
- Uses UQD connectors and stainless steel corrugated tubing

Applications



HPC



AI



Deep Learning Training



Data Analytics

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